BFi OPTiLAS and XMA Sign Distribution Agreement

XMA Corporation and BFi OPTiLAS announce the signing of a distribution agreement. Under terms of the agreement, BFi OPTiLAS will distribute XMA's full line of standard RF & microwave components including terminations, attenuators, and other passive products in the European markets.

Connor-Winfield Purchases AG Communication's Manufacturing Facility and Assets

The Connor-Winfield Corporation announces that it is purchasing from AG Communication Systems (AGCS) its manufacturing facility in Genoa, Illinois. AGCS is a wholly owned subsidiary of Lucent Technologies Inc. (Lucent) and in April, 2004, Lucent announced the facility would close. The terms of the transaction between Connor-Winfield and AGCS were not disclosed.

Cardinal Components Announces Partnership

Cardinal Components Inc. announces its latest distribution partnership with Dependable Component Supply. DCS has been in business for over 16 years and distributes a wide range of electronic components from crystals and oscillators to integrated circuits. DCS is headquartered in Deerfield Beach, Florida.

Richardson's Interconnect Group Signs Distribution Agreement with Fractus

Richardson Electronics announces it has signed a distribution agreement with Fractus, a pioneer developer and manufacturer of antennas for the telecommunications, electronics and military industries. Under the terms of the agreement, Richardson will operate as a global distributor for Fractus' complete line of embedded antennas for short-range wireless applications, filling a need in Richardson's components solutions line card. Richardson's product offering will now encompass an array of components for the emerging Broadband Wireless Access market to accommodate WiFi, WiMAX, Zigbee, and Bluetooth&reg technologies.

Henkel Announces Opening of Research and Applications Center

The electronics group of Henkel announces the opening of its Research and Applications Center. The 53,000 square foot state-of-the-art facility in Irvine, CA will house R&D and applications engineering for the company's die attach, semiconductor underfill, encapsulant, and semiconductor mold compound products. The facility is the new global headquarters for the electronics group of Henkel and marks the first official opening of several planned new worldwide facilities for the electronic materials leader.

austriamicrosystems and Nu Horizons Announce Distribution Partnership Agreement

austriamicrosystems AG and Nu Horizons Electronics Asia Pte. Ltd. announce a partnership agreement to distribute austriamicrosystems' ASSP and Standard Linear IC products throughout Asia Pacific.

Spectrum Delivers Development Platforms to US Defense Contractor

Spectrum Signal Processing Inc. announces that an unnamed US defense contractor has purchased two SDR-3000 MRDP platforms for use in its internal military communications research and development programs. The order is the first design-in for Spectrum's flexComm&#153 SDR-3000 MRDP, a rapid-prototyping development platform designed for military communications (MILCOM) applications, following its introduction in November 2004.

Olympus-ITA to Supply Wafer and Defect Review Systems to Major Integrated Device Manufacturer

Olympus Integrated Technologies America (ITA), a subsidiary of Olympus Corporation of Japan announces an agreement with one of the world's largest US integrated device manufacturers (IDMs). Under the agreement, the IDM will purchase additional 300 mm wafer inspection systems from Olympus. The first order for Olympus' AL3100 systems was in Q1 2004, with the second order delivered at the end of 2004. The systems will provide both inspection and defect review capabilities.

XEMICS SA Launches Hong Kong Branch Office

XEMICS SA announces its expanded presence in the Asia Pacific market. XEMICS' new Asia Pacific branch office will be based centrally in the heart of Hong Kong. The Asian branch office's primary goal is to intensify sales and marketing activities in South East Asia. At present, the Asian market accounts for 20% of XEMICS' sales

turnover. With this expansion, the company is aiming to increase that figure to 30% by the end of 2005. By being on-site, the Asian Branch Office can provide Asian customers with full services and application support.

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